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# PATENTS ABSTRACTS OF JAPAN

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## (54) ELECTRONIC PARTS MOUNTING DEVICE

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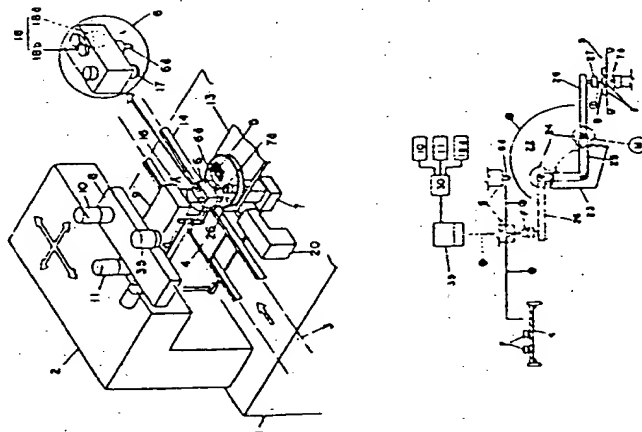
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**PURPOSE:** To precisely and automatically perform mounting on a board by controlling the nozzle of a transfer head so that it can be placed on the center of a flip chip on the basis of an observed result of a visual inspection.

**CONSTITUTION:** When XY directional moving devices 8, 9 are driven to move a camera 17 upward of a board 4, a position discrepancy of a printed pattern is observed and a suction part 27 of an arm 26 of an inside and outside reversing device 22 approaches a wafer 5, the suction part 27 is sucked on a bump forming face by a pin 7a to take up a flip chip F. Next, an xyθ-directional position discrepancy is observed on condition that the flip chip F is inverted. A transfer head 6 is moved on the basis of this observed result, the flip chip 27 is taken up and an XY-directional moving devices 8, 9 are driven so that a nozzle 6a can be placed on the center of the flip chip F. Thereby the inside and outside of the flip chip F is reversed to precisely mount on the board 4.



## LEGENDE zu den Bibliographiedaten

(54) Titel der Patentanmeldung

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